



## Material Content Data Sheet



<b>Sales Product Name</b>	ITD50N04S4L-07			<b>Issued</b>	22. January 2018			
<b>MA#</b>	MA001786784							
<b>Package</b>	PG-TO252-5-11			<b>Weight*</b>	355.93 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.029	0.57	0.57	5701	5701
leadframe	inorganic material	phosphorus	7723-14-0	0.061	0.02		172	
	non noble metal	iron	7439-89-6	0.205	0.06		575	
wire	non noble metal	copper	7440-50-8	204.243	57.37	57.45	573834	574581
	non noble metal	aluminium	7429-90-5	4.231	1.19	1.19	11887	11887
encapsulation	organic material	carbon black	1333-86-4	1.380	0.39		3877	
	plastics	epoxy resin	-	24.151	6.79		67854	
leadfinish	inorganic material	silicondioxide	60676-86-0	112.474	31.60	38.78	316004	387735
	non noble metal	tin	7440-31-5	5.072	1.43	1.43	14252	14252
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	nickel	7440-02-0	0.076	0.02	0.02	214	215
solder	non noble metal	tin	7440-31-5	0.040	0.01		113	
	noble metal	silver	7440-22-4	0.050	0.01		141	
*deviation	non noble metal	lead	7439-92-1	1.913	0.54	0.56	5375	5629
	< 10%				Sum in total:		100.00	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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